



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Jing Cheng Lin, et al. § Docket No.: 24061.485
Serial No.: 10/618,536 § (TSMC2002-0360)
Filing Date: June 11, 2003 § Examiner: Thien F. Tran
For: Adhesion Copper and Etch Stop § Art Unit: 2811
Layer for Copper Alloy § Conf. No.: 5026
§

TRANSMITTAL

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Enclosed for filing in the above-identified patent application.

1. Response to Restriction Requirement;
2. Petition for Extension of Time (1-month);
3. Check in the amount of \$110.00; and
4. Return Receipt Postcard

The Director is authorized to charge any deficiency fees or credit any overpayments to Deposit Account No. 08-1394 of Haynes and Boone, LLP.

Respectfully submitted,

David M. O'Dell
Reg. No. 42,044

Date: 10-20-04

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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Box: Amendments, Commissioner For Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on the date indicated below:

Name: Bonnie Boyce
Date: 10-20-04